

**ELECTROPLATING APPARATUS AND METHOD**  
**USING A COMPRESSIBLE CONTACT**

ABSTRACT

A metal plating apparatus is described which includes a compressible member (21) having a conductive surface covering substantially all of the surface of the substrate (1) to be plated. The plating current is thereby transmitted over a wide area of the substrate (1), rather than a few localized contact points. The compressible member (21) is porous so as to absorb the plating solution and transmit the plating solution to the substrate (1). The wafer (1) and compressible member (21) may rotate with respect to each other. The compressible member (21) may be at cathode potential or may be a passive circuit element.

FIG. 2